**PRODUCT/PROCESS CHANGE NOTICE (PCN)**

<table>
<thead>
<tr>
<th>PCN #: L0110-04</th>
<th>DATE: 10/19/01</th>
</tr>
</thead>
<tbody>
<tr>
<td>Product Affected: PA48 &amp; PA56 (TSSOP) packages of all Logic devices</td>
<td>MEANS OF DISTINGUISHING CHANGED DEVICES:</td>
</tr>
<tr>
<td>Date Effective: October 19, 2001</td>
<td>□ Product Mark</td>
</tr>
<tr>
<td>Contact: Bimla Paul</td>
<td>□ Back Mark</td>
</tr>
<tr>
<td>Title: Q.A. Manager</td>
<td>□ Date Code</td>
</tr>
<tr>
<td>Phone #: (408) 654-6419</td>
<td>□ Other</td>
</tr>
<tr>
<td>Fax #: (408) 492-8362</td>
<td>Samples: N/A</td>
</tr>
<tr>
<td>E-mail: <a href="mailto:bimla.paul@idt.com">bimla.paul@idt.com</a></td>
<td>Attachment:: Yes No</td>
</tr>
</tbody>
</table>

**DESCRIPTION AND PURPOSE OF CHANGE:**

- □ Die Technology
- □ Wafer Fabrication Process
- □ Assembly Process
- □ Equipment
- □ Material
- □ Testing
- □ Manufacturing Site
- □ Data Sheet
- □ Other

To comply with the requirement of reflow temperature of +235°C +5/-0°C per Assembly Process IPC/JEDEC J-STD-020A. Moisture sensitivity level of all TSSOP 48 & 56 Logic devices will be changed from level 1 (Non-Moisture Sensitive) to level 3 (Moisture Sensitive).

Moisture sensitivity label per IPC/JEDEC J-STD-033 will be applied to the dry pack effective 10/19/2001 (See attachment # 1).

**RELIABILITY/QUALIFICATION SUMMARY:**

Moisture sensitivity level is changed from level 1 to level 3.

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ___________________________  □ Approval for shipments prior to effective date.

Name/Date: ___________________________  E-Mail Address: ___________________________

Title: ___________________________  Phone#/Fax#: ___________________________

**CUSTOMER COMMENTS:**

______________________________

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: ___________________________  DATE: ___________________________

IDT FRA-1509-01 REV. 00 09/18/01  Page 1 of 1  Refer To QCA-1795
Moisture Sensitivity Label for level 3

CAUTION
This Bag Contains MOISTURE-SENSITIVE DEVICES
LEVEL 3

1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH)
2. Peak package body temperature: [ ] 225°C [ ] 240°C
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
   a) Mounted within **168 hours** of factory conditions [ ] 30°C/60%
   b) Stored at ≤ 10% RH
4. Devices require bake, before mounting, if:
   a) Humidity Indicator Card is >10% when read at 23 ± 5°C,
   b) 3a or 3b is not met.
5. If baking is required, devices may be baked for 48 hours at 125 ± 5°C

Note: If device containers cannot be subjected to high temperature or shorter bake times are desired,
reference IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: ____________________________
If Blank, see adjacent bar code label
Note: Level and body temperature defined by IPC/JEDEC J-STD-020